

# HSM122

Silicon Epitaxial Planar Diode for High Voltage Switching

REJ03G1299-0100 Rev.1.00 Oct 27, 2005

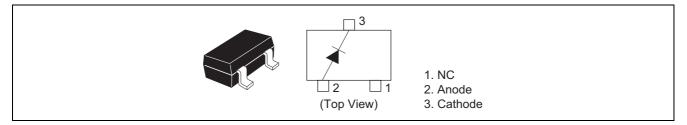
### Features

- High reverse voltage. ( $V_R = 400 \text{ V}$ )
- MPAK package is suitable for high density surface mounting and high speed assembly.

### **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSM122	F8	MPAK	PLSP0003ZC-A (MPAK)

### **Pin Arrangement**





### **Absolute Maximum Ratings**

			$(Ta = 25^{\circ}C)$
Item	Symbol	Value	Unit
Peak reverse voltage	V <sub>RM</sub>	420	V
Reverse voltage	V <sub>R</sub>	400	V
Peak forward current	I <sub>FM</sub>	625	mA
Non-Repetitive peak forward surge current	I <sub>FSM</sub> * <sup>1</sup>	1	А
Average rectified current	lo	150	mA
Power dissipation	Pd * <sup>2</sup>	150	mW
Junction temperature	Тј	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. Value at duration of 1s.

2. Standard substrate mounting (20mm  $\times$  15mm  $\times$  0.8t mm, With Polyimide board)

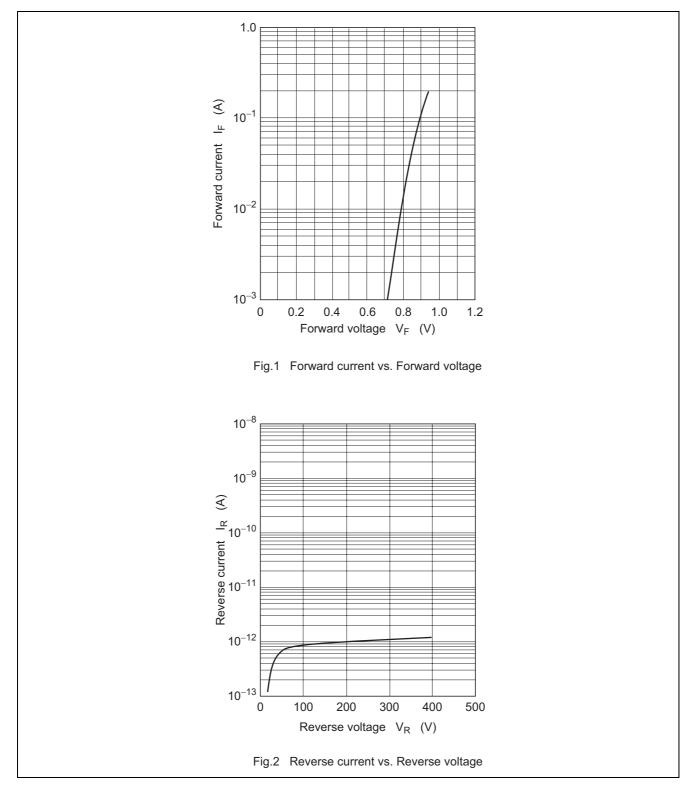
## **Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

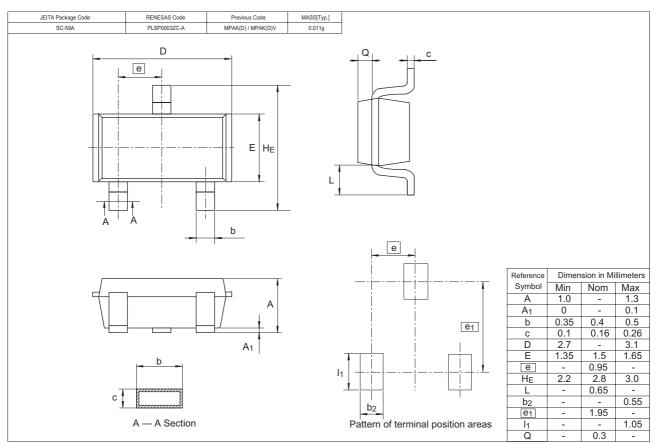
ltem	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	VF	-	_	1.2	V	I <sub>F</sub> = 100 mA
Reverse current	I <sub>R</sub>	-	_	1.0	μΑ	V <sub>R</sub> = 400 V
Capacitance	С	-	_	10	pF	$V_R = 0 V$ , f = 1 MHz
Reverse recovery time	trr			20	μs	$I_F=30~mA,~V_R=10~V,~R_L=2~k\Omega$



### **Main Characteristic**



### **Package Dimensions**





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